



January 2008



# FPF1007-FPF1009

## IntelliMAX™ Advanced Load Products

### Features

- 1.2 to 5.5V Input Voltage Range
- Typical  $R_{ON}$  = 30 mΩ @  $V_{IN}$  = 5.5V
- Typical  $R_{ON}$  = 40 mΩ @  $V_{IN}$  = 3.3V
- Fixed Three Different Turn-on Rise-time 10µs/80µs/1ms
- Low < 10µA @  $V_{IN}$  = 3.3V Quiescent Current
- Internal ON Pin Pull Down
- Output Discharge Function
- ESD Protection above 8000V HBM and 2000V CDM
- RoHS Compliant

### Applications

- PDAs
- Cell Phones
- GPS Devices
- MP3 Players
- Digital Cameras
- Peripheral Ports
- Hot Swap Supplies
- Notebook Computer

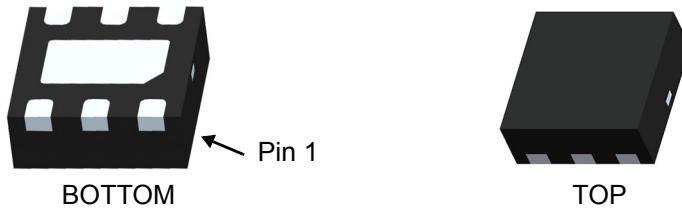


### General Description

The FPF1007/8/9 are low RDS P-Channel MOSFET load switches offered in a selection of 10µs, 80µs, and 1ms slew rate turn-on options for transient/in-rush current control. To support trends in mobile application requirements the minimum operating input voltage has been reduced down to 1.2V, the input current leakage has been minimized to extend battery life, and the ESD-protection has been designed to withstand a minimum of 8KV (HBM) and 2KV(CDM).

The switch is controlled by an active-high logic input (ON pin) allowing it to interface directly with a low voltage control signal. An internal ON pin pull down resistor protects against an unintentional device turn-on while in the initial state. An On-chip pull-down resistor on the output is enabled when the switch is turned-off and provides a quick and robust discharge of the output load.

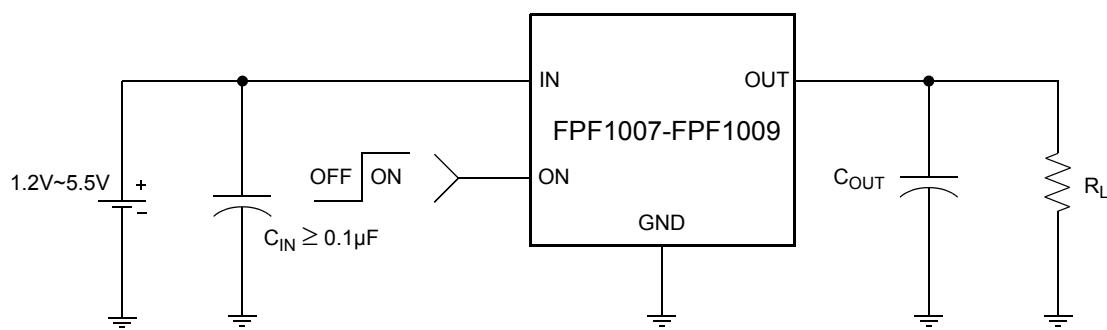
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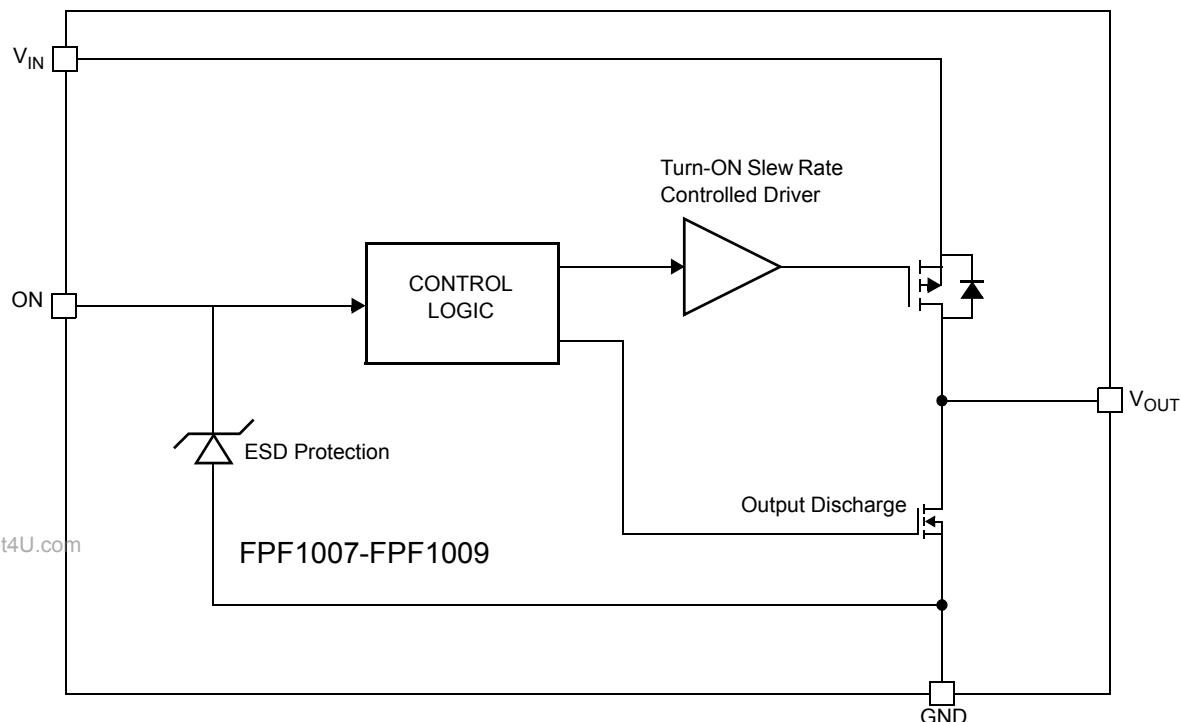
### Ordering Information

Part	Switch $R_{ON}$ @ 5.5V [Typ.]	Rise Time [Typ.]	Output Discharge [Typ.]	ON Pin Activity
FPF1007	30mΩ, PMOS	10µs	60Ω	Active HI
FPF1008	30mΩ, PMOS	80µs	60Ω	Active HI
FPF1009	30mΩ, PMOS	1ms	60Ω	Active HI

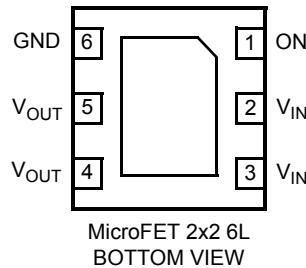
### Typical Application Circuit



### Functional Block Diagram



## Pin Configuration



## Pin Description

Pin	Name	Function
4, 5	V <sub>OUT</sub>	Switch Output: Output of the power switch
2, 3	V <sub>IN</sub>	Supply Input: Input to the power switch and the supply voltage for the IC
6	GND	Ground
1	ON	ON/OFF Control Input

## Absolute Maximum Ratings

Parameter		Min.	Max.	Unit
V <sub>IN</sub> , V <sub>OUT</sub> , ON to GND		-0.3	6	V
Maximum Continuous Switch Current			1.5	A
Power Dissipation @ T <sub>A</sub> = 25°C (Note 1)			1.2	W
Storage Junction Temperature		-65	150	°C
Operating Temperature Range		-40	85	°C
Thermal Resistance, Junction to Ambient			86	°C/W
Electrostatic Discharge Protection	HBM	8000		V
	CDM	2000		V

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## Recommended Operating Range

Parameter		Min.	Max.	Unit
V <sub>IN</sub>		1.2	5.5	V
Ambient Operating Temperature, T <sub>A</sub>		-40	85	°C

## Electrical Characteristics

V<sub>IN</sub> = 1.2 to 5.5V, T<sub>A</sub> = -40 to +85°C unless otherwise noted. Typical values are at V<sub>IN</sub> = 3.3V and T<sub>A</sub> = 25°C.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
<b>Basic Operation</b>						
Operating Voltage	V <sub>IN</sub>		1.2		5.5	V
Quiescent Current	I <sub>Q</sub>	I <sub>OUT</sub> = 0mA, V <sub>IN</sub> = 3.3V, V <sub>ON</sub> = Enabled		8		μA
		I <sub>OUT</sub> = 0mA, V <sub>IN</sub> = 5.5V, V <sub>ON</sub> = Enabled			15	
Off Supply Current	I <sub>Q(off)</sub>	V <sub>ON</sub> = GND, V <sub>OUT</sub> = OPEN			1	μA
Off Switch Current	I <sub>SD(off)</sub>	V <sub>ON</sub> = GND, V <sub>OUT</sub> = GND		0.1	1	μA

## Electrical Characteristics Cont.

$V_{IN}$  = 1.2 to 5.5V,  $T_A$  = -40 to +85°C unless otherwise noted. Typical values are at  $V_{IN}$  = 3.3V and  $T_A$  = 25°C.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
On-Resistance	$R_{ON}$	$V_{IN} = 5.5V, I_{OUT} = 200mA, T_A = 25^\circ C$		30	40	mΩ
		$V_{IN} = 3.3V, I_{OUT} = 200mA, T_A = 25^\circ C$		40	55	
		$V_{IN} = 1.5V, I_{OUT} = 200mA, T_A = 25^\circ C$		100	130	
		$V_{IN} = 1.2V, I_{OUT} = 200mA, T_A = 25^\circ C$		175	250	
		$V_{IN} = 3.3V, I_{OUT} = 200mA, T_A = -40^\circ C \text{ to } +85^\circ C$	20		65	
Output Pull Down Resistance	$R_{PD}$	$V_{IN} = 3.3V, V_{ON} = 0V, T_A = 25^\circ C$		60		Ω
ON Input Logic Low Voltage	$V_{IL}$	$V_{IN} = 1.2V \text{ to } 5.5V$			0.4	V
ON Input Logic High Voltage	$V_{IH}$	$V_{IN} = 1.2V \text{ to } 5.5V$	1			V
ON Input Leakage (On)		$V_{ON} = V_{IN} = 5.5V$	-1		10	μA
ON Input Leakage (Off)		$V_{ON} = GND$	-1		1	μA
<b>Dynamic</b>						
<b>FPP1007</b>						
Turn On	$t_{ON}$	$V_{IN} = 3.3V, R_L = 500\Omega, R_{L\_CHIP} = 60\Omega,$ $C_{OUT} = 0.1\mu F, T_A = 25^\circ C$		12		μs
Rise Time	$t_R$			10		μs
Turn Off	$t_{OFF}$			40		μs
Fall Time	$t_F$			15		μs
<b>FPP1008</b>						
Turn On	$t_{ON}$	$V_{IN} = 3.3V, R_L = 500\Omega, R_{L\_CHIP} = 60\Omega,$ $C_{OUT} = 0.1\mu F, T_A = 25^\circ C$		125		μs
Rise Time	$t_R$			80		μs
Turn Off	$t_{OFF}$			40		μs
Fall Time	$t_F$			15		μs
<b>FPP1009</b>						
Turn On	$t_{ON}$	$V_{IN} = 3.3V, R_L = 500\Omega, R_{L\_CHIP} = 60\Omega,$ $C_{OUT} = 0.1\mu F, T_A = 25^\circ C$		2		ms
Rise Time	$t_R$			1		ms
Turn Off	$t_{OFF}$			40		μs
Fall Time	$t_F$			15		μs

**Note 1:** Package power dissipation on 1square inch pad, 2 oz. copper board.

## Typical Characteristics

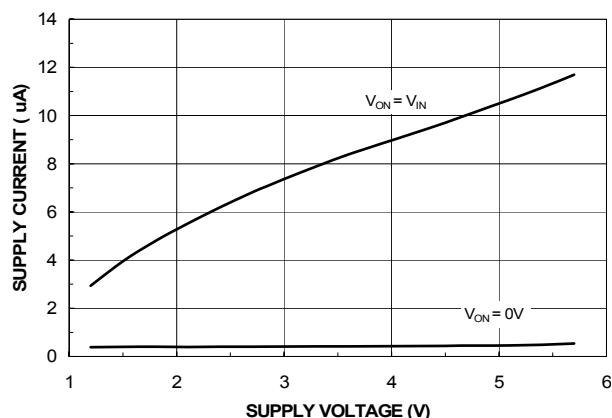


Figure 1. Quiescent Current vs. Input Voltage

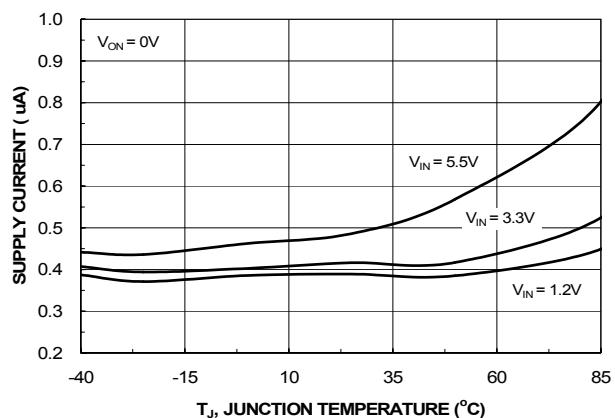


Figure 2. Quiescent Current vs. Temperature

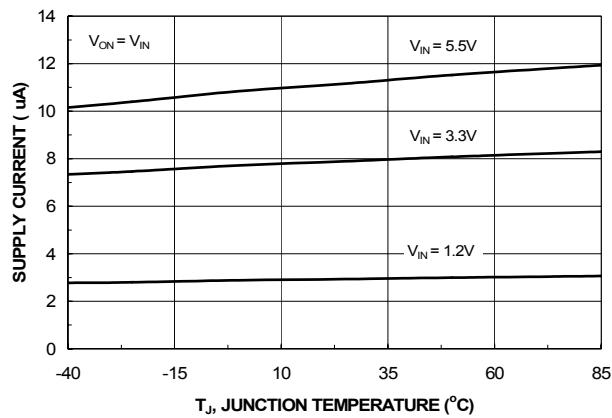
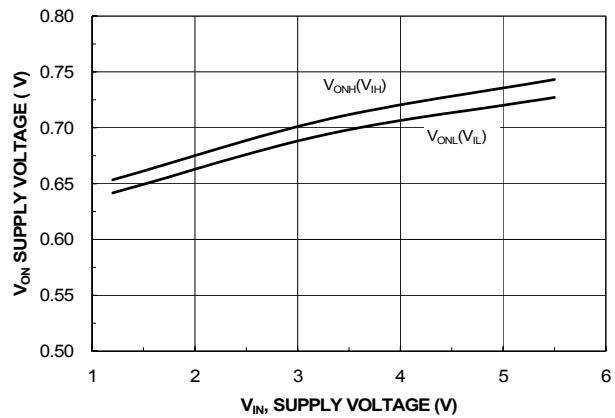
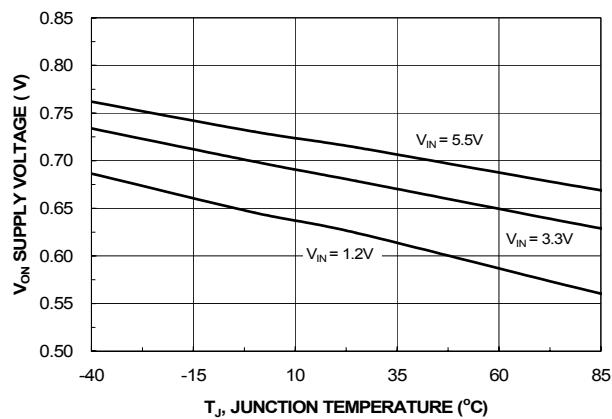
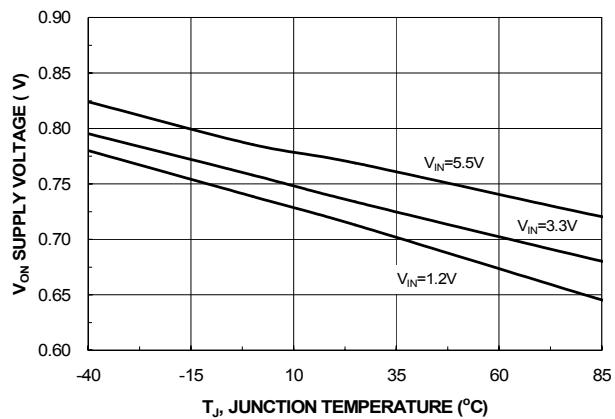


Figure 3. Quiescent Current vs. Temperature

Figure 4.  $V_{ON}$  Voltage vs. Input VoltageFigure 5.  $V_{ON}$  Low Voltage vs. TemperatureFigure 6.  $V_{ON}$  High Voltage vs. Temperature

## Typical Characteristics

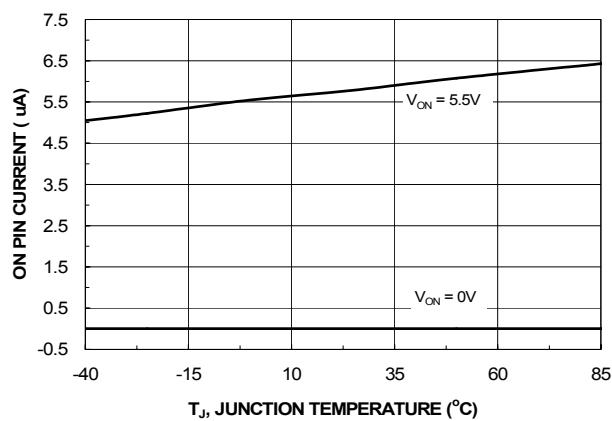
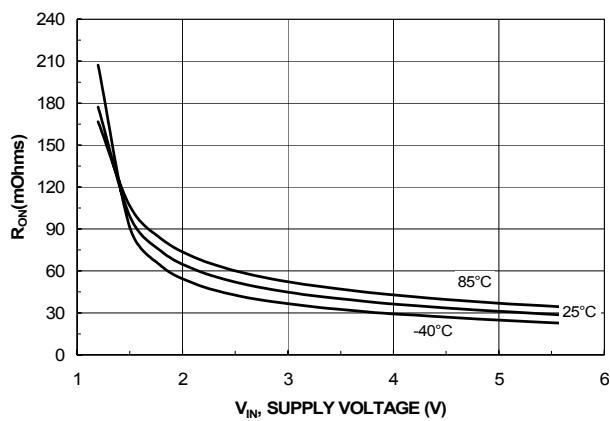
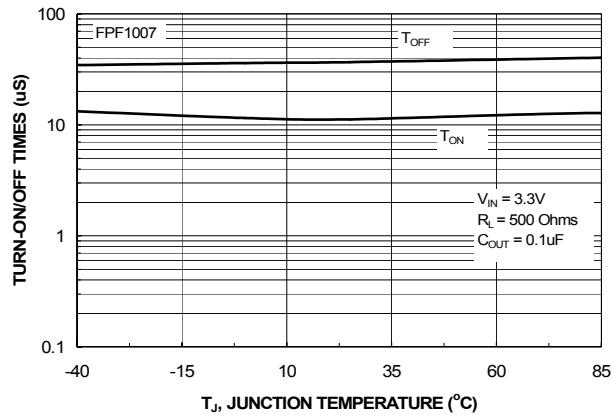
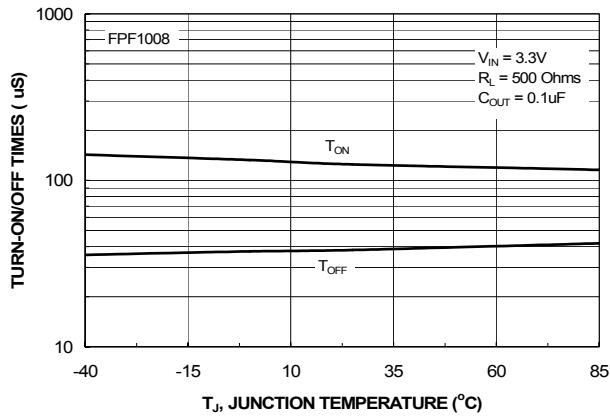
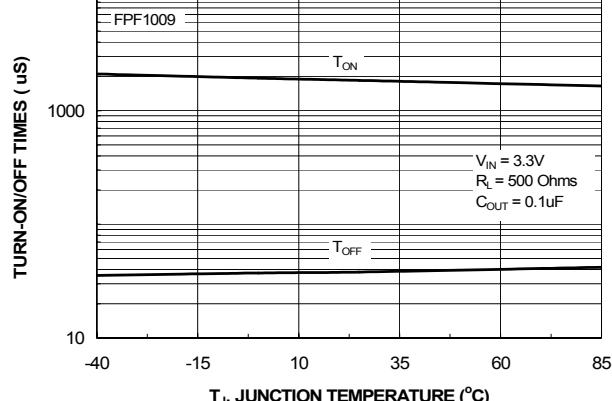
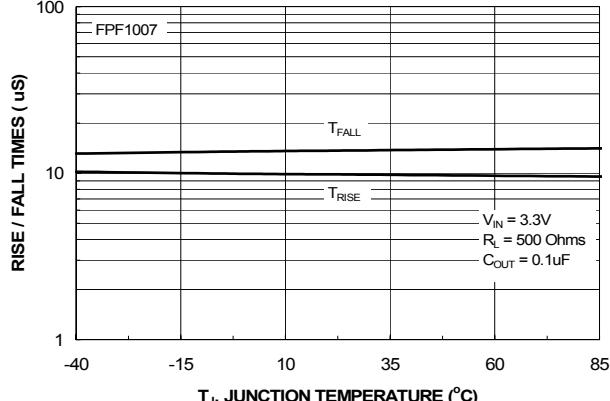
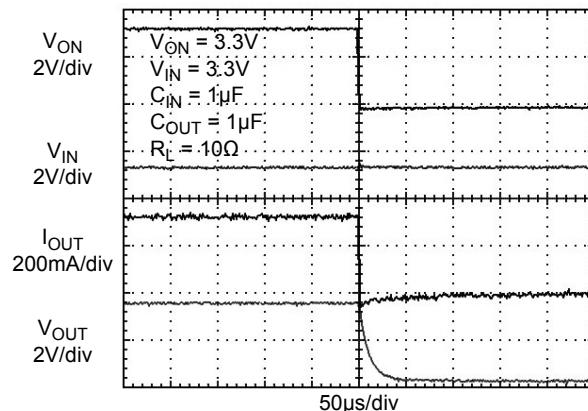
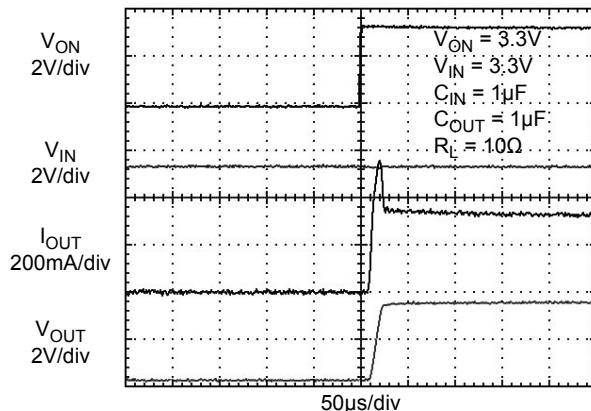
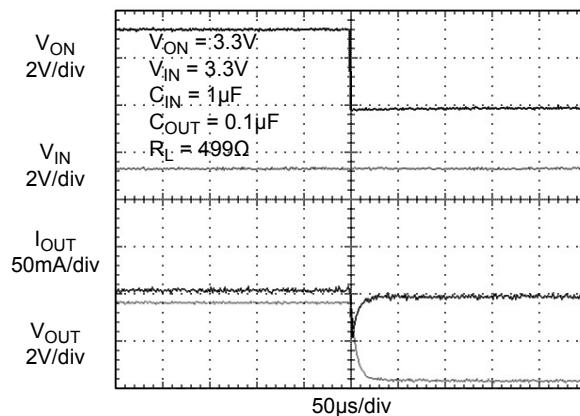
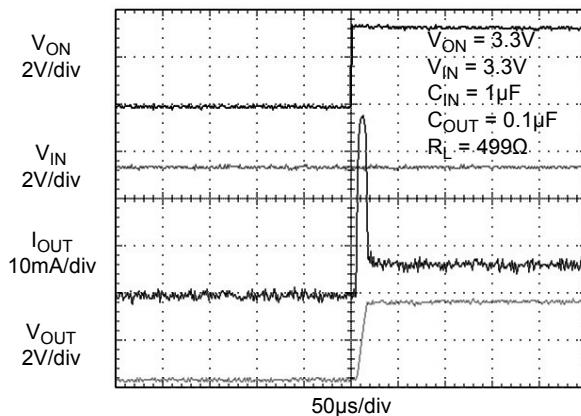
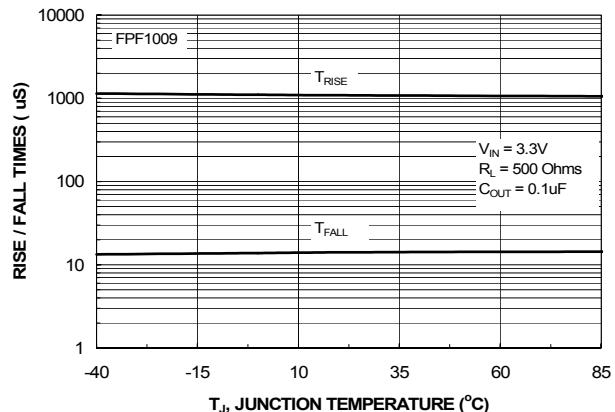
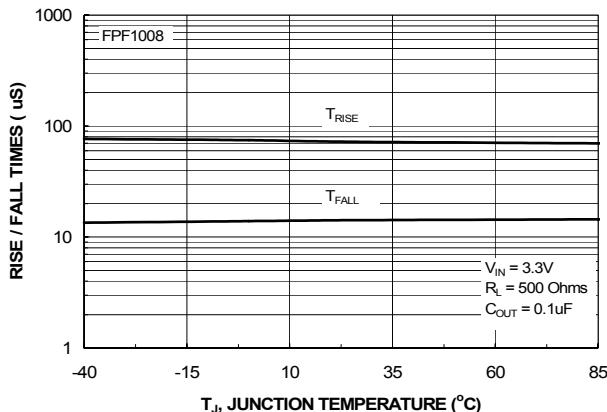


Figure 7. On Pin Current vs. Temperature

Figure 8.  $R_{ON}$  vs.  $V_{IN}$ Figure 9. FPF1007  $T_{ON}$  /  $T_{OFF}$  vs. TemperatureFigure 10. FPF1008  $T_{ON}$  /  $T_{OFF}$  vs. TemperatureFigure 11. FPF1009  $T_{ON}$  /  $T_{OFF}$  vs. TemperatureFigure 12. FPF1007  $T_{RISE}$  /  $T_{FALL}$  vs. Temperature

## Typical Characteristics



## Typical Characteristics

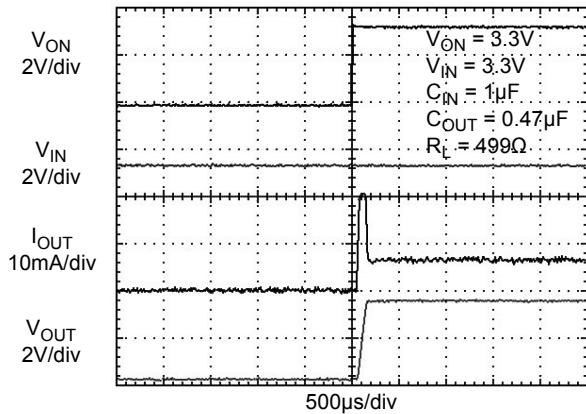


Figure 19. FPF1008 Turn ON Response

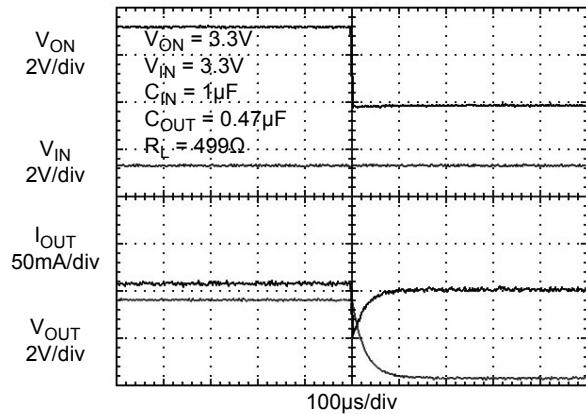
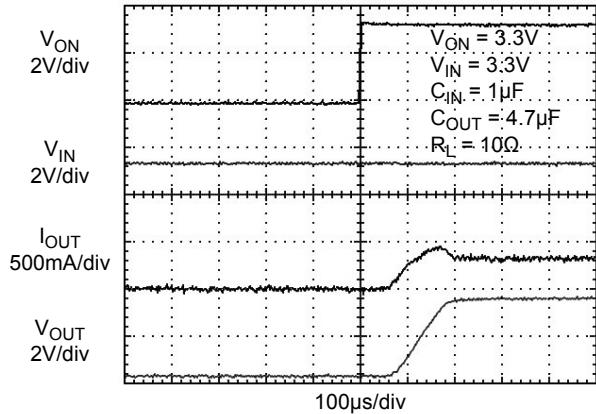
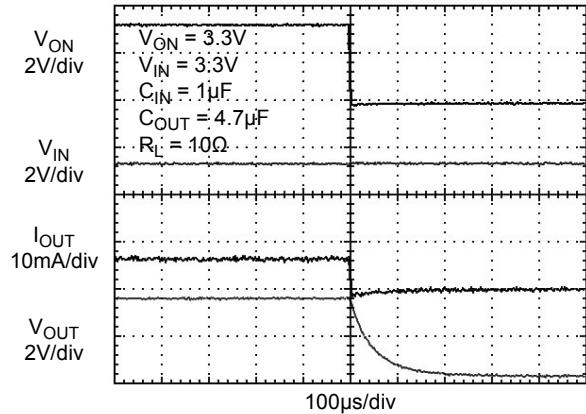
Figure 20. FPF1008 Turn OFF Response  
Load current is discharged through On-chip output discharge resistor.Figure 21. FPF1008 Turn ON Response ( $C_{OUT} = 4.7\mu F$ )

Figure 22. FPF1008 Turn OFF Response

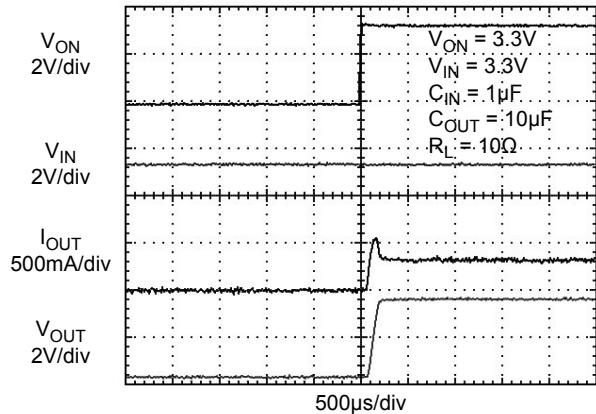
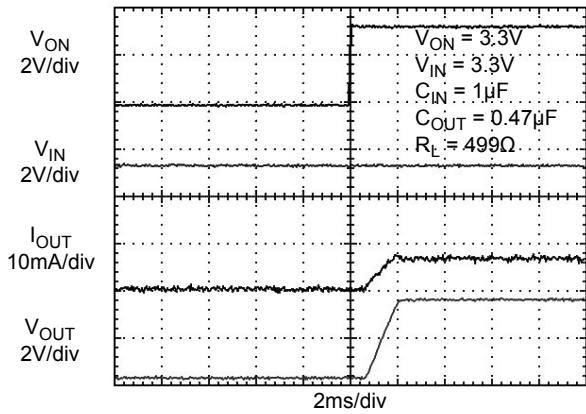
Figure 23. FPF1008 Turn ON Response ( $C_{OUT} = 10\mu F$ )

Figure 24. FPF1009 Turn ON Response

## Typical Characteristics

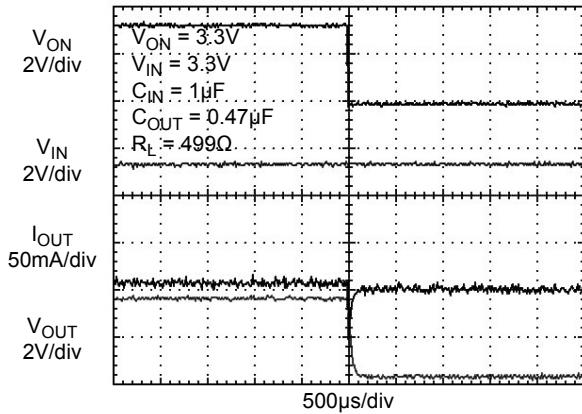


Figure 25. FPF1009 Turn OFF Response  
Load current is discharged through On-chip output discharge resistor.

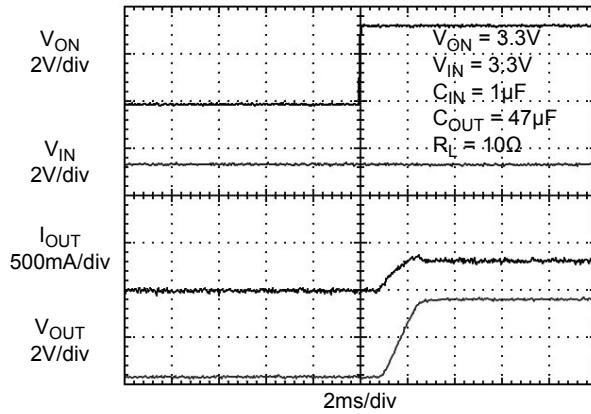


Figure 26. FPF1009 Turn ON Response ( $C_{OUT} = 47\mu F$ )

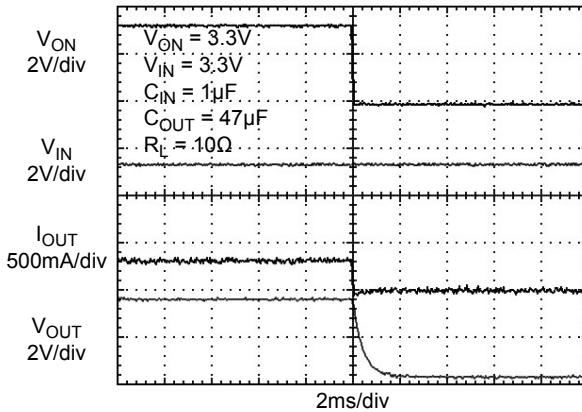


Figure 27. FPF1009 Turn OFF Response

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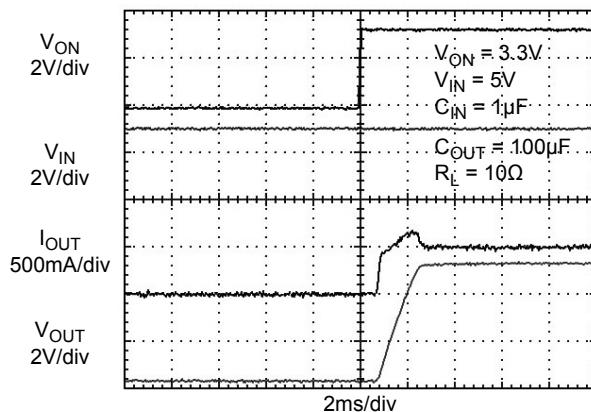
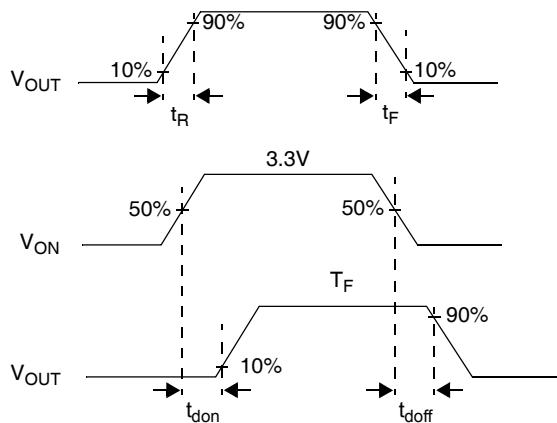


Figure 28. FPF1009 Turn ON Response  
( $C_{OUT} = 100\mu F$ ,  $V_{IN} = 5V$ )

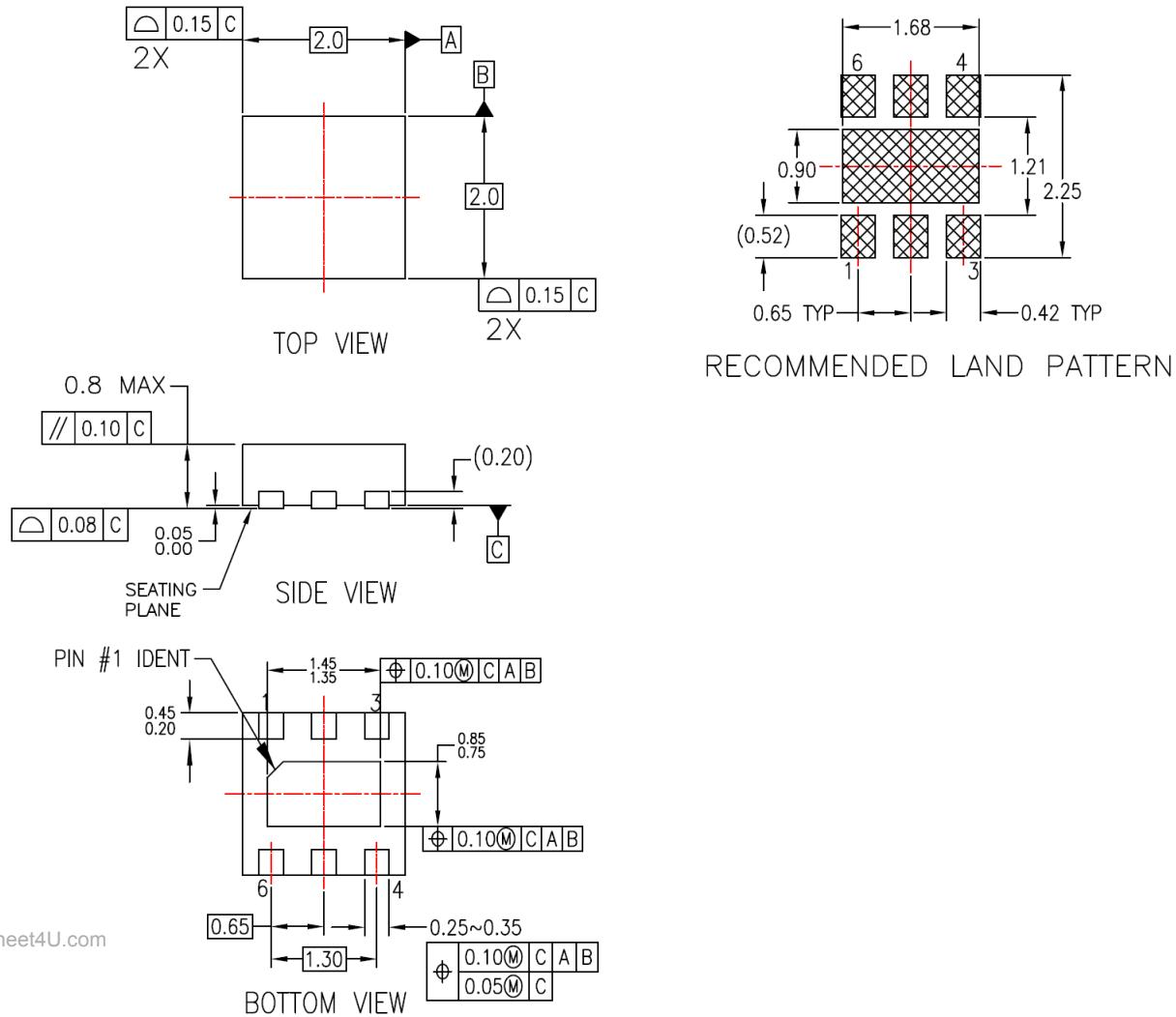
## Timing Diagram



where:

- $t_{ON}$  = Turn ON Time
- $t_{OFF}$  = Turn OFF Time
- $t_{don}$  = Turn ON Delay Time
- $t_{dooff}$  = Turn OFF Delay Time
- $t_R$  = Rise Time
- $t_F$  =  $V_{OUT}$  Fall Time
- $t_{ON}$  =  $t_R + t_{don}$
- $t_{OFF}$  =  $t_F + t_{dooff}$

## Dimensional Outline and Pad Layout



### NOTES:

- A. NON-CONFORMS TO JEDEC REGISTRATION,
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER  
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Datasheet Identification	Product Status	Definition
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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